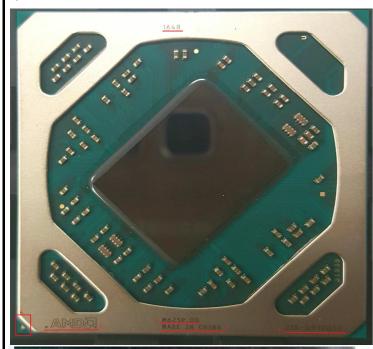
料號

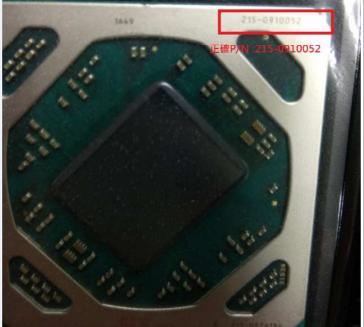
10HB5-12POLA-50R

品名規格

CHIP Polaris 20 XL AMD SMD HFCBGA1401 P/N=215-0910052

零件樣品圖:





外觀文字面檢驗重點:

- 1. AMD Logo(不可變)
- 2.1648: Date Code (可變)
- 3.M625P.00: Wafer foundry's lot NO. (可變)
- 4. MADE IN CHINA/TAIWAN/MALAYSIA(不可變)
- 5.215-0910052: P/N(不可變)
- 6. PIN 1(不可變)

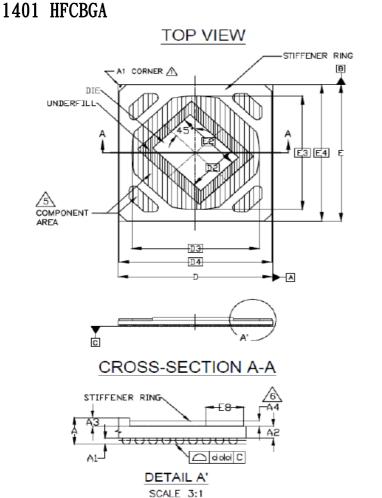
2017/5/24來料出現2種P/N:右上角215-0910052 (正確P/N)右下角215-0876184(錯誤P/N),原因為 Polaris 10 XT sorting 為Polaris 20*料件,右 下角顯示的是舊Polaris 10 XT的P/N,右上角為正 確P/N,廠商確認此料以右上角P/N: 215-0910052 為主.現將出現2種P/N料件列入IQC檢驗允收規範. (附原廠說明文件)



2017/10/29來料出現MADE IN TAIWAN料件與檢驗重點MADE IN CHINA不符,經RD hot-run驗證測試PASS,現將MADE IN TAIWAN料件列入IQC檢驗允收規範.

2019/03/11來料出現MADE IN MALAYSIA料件與檢驗重點MADE IN CHINA不符,經RD hot-run驗證測試PASS,現將MADE IN MALAYSIA料件列入IQC檢驗允收規範.

機構尺寸工程圖:



BOTTOM VIEW

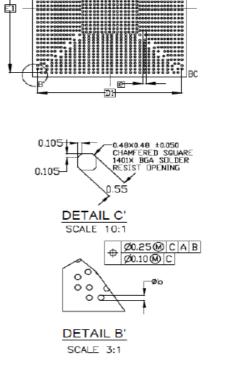


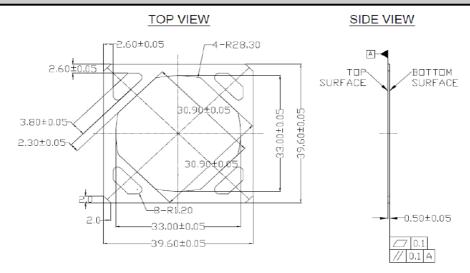
Table 7-1 -L4 Physical Dimensions (mm)

Sym bol	Minimum	Normal	Maximum	Note
A	2.21	2.40	2.59	See side view.
A1	0.25	0.35	0.45	See side view.
A2	1.05	1.15	1.25	See side view.
A3	0.80	0.85	0.90	See side view.
A4	0.50	0.55	0.60	See side view.
øb	_	_	_	See note 3 below and bottom view.
D	39.90	40.00	40.10	See top view.
D1	_	37.40	_	See bottom view.
D2		13.80	_	See top view.
D3	_	33.00	_	See top view.
D4	_	39.60	_	See top view.
E	39.90	40.00	40.10	See top view.
E1	_	37.40	_	See bottom view.
E2	_	17.63	_	See top view.
E3	_	33.00	_	See top view.

Symbol	Minimum	Normal	Maximum	Note
E4	_	39.60	_	See top view.
E8		3.30		See side view.
e	0.80 BSC (basic)			See bottom view.
ddd	_	_	0.23	See side view.
N	1401			Number of pins.

Note:

- This is a multi-pitch (more than one pitch or distance on the substrate between the balls) package.
- 2. The SMT (surface mount technology) component height from the substrate top surface is 0.65 mm maximum.
- 3. Before solder ball attach reflow, the solder ball diameter øb is 0.50 nominal. After solder ball attach reflow, the solder ball diameter øb is 0.55 \pm 0.10.



Note: The following notes are for the "Polaris 20"-L4 stiffener ring with 0.50 mm thickness:

- The maximum standard radius is 0.20 mm.
- The maximum burr size is 0.05 mm.
- The material is copper (C1100).
- The surface finish is Ni plating at 5 μM to 15 μM .

IQC電氣、機構檢驗重點:

- 1. 量測各部尺寸須與規格值相符.
- 2. 檢視產品外觀,表面無異物,且不得有任何破損及變形.

μ-EDX 有害物質檢測:

 μ -EDX 需依照HCSR 有害物質管制規範實施檢測,並參照FP-0743-05-03 IQC EDX Test Guide 規範。

Date: 2017/03/02	Rev. 00	首次發行
Date: 2017/05/24	Rev. 01	update右上角、右下角同時出現不同P/N料件至允收規範
Date: 2018/02/07	Rev. 02	update MADE IN TAIWAN料件至允收規範
Date: 2019/03/11	Rev. 03	update MADE IN MALAYSIA料件至允收規範